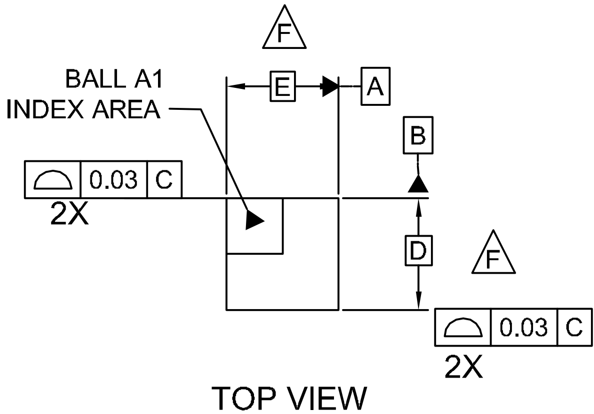
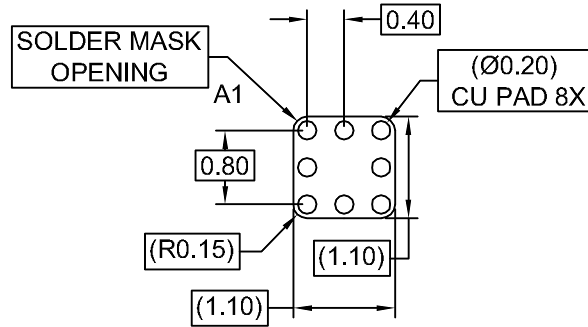
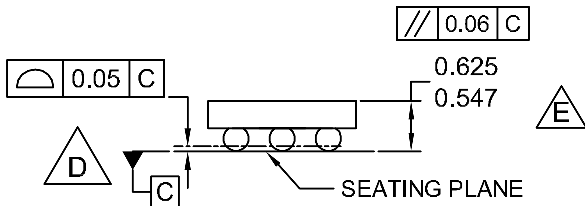
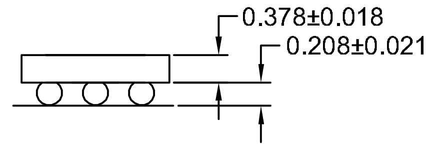
REV	DESCRIPTION	DATE	BY/SITE
1	INITIAL DRAWING RELEASE.	2-21-2007	H. ALLEN
2	UPDATED PACKAGE THICKNESS DIMENSIONS, REMOVED BSL LINE.	2-15-2008	L. ENGLAND
3	UPDATED PACKAGE THICKNESS DIMENSIONS.	2-22-2008	L. ENGLAND



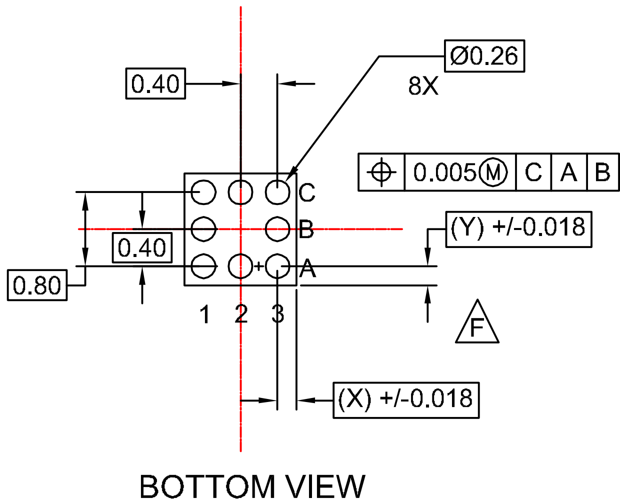
TOP VIEW







SIDE VIEWS



BOTTOM VIEW

NOTES:

A. NO JEDEC REGISTRATION APPLIES.

B. DIMENSIONS ARE IN MILLIMETERS.

C, DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

D. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

E. PACKAGE TYPICAL HEIGHT IS 586 MICRONS ± 39 MICRONS (547-625 MICRONS).

F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

G. BALL COMPOSITION: Sn95.5-Ag3.9-Cu0.6

I. DRAWING FILENAME: MKT-UC008Acrev3.

FSC INTERNAL NOTE: TYPE 1 WLCSP IS PROVIDED BY UNITIVE/AMKOR ONLY!

APPROVALS		DATE
DRAWN	L. ENGLAND	2-22-2008
DFTG. CHK.	S. MARTIN	2-22-2008
ENGR. CHK.		

FAIRCHILD SEMICONDUCTOR®
333 Western Ave., So. Portland, Maine, USA

8BALL, TYPE 1 WL-CSP, .4MM PITCH, GENERIC DRAWING

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]	N/A	N/A	MKT-UC008AC	3

DO NOT SCALE DRAWING

SHEET 1 of 1